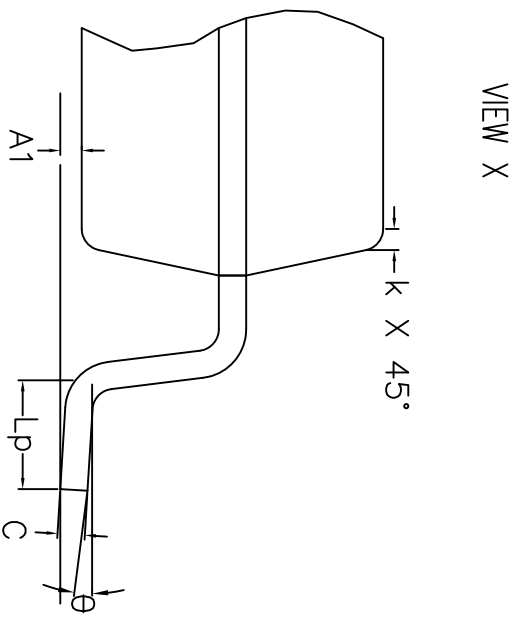
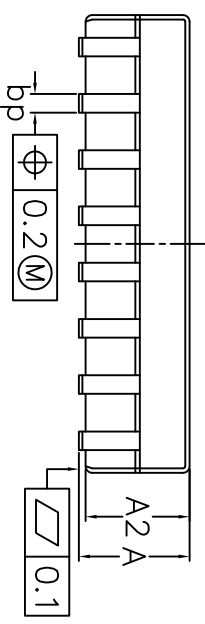
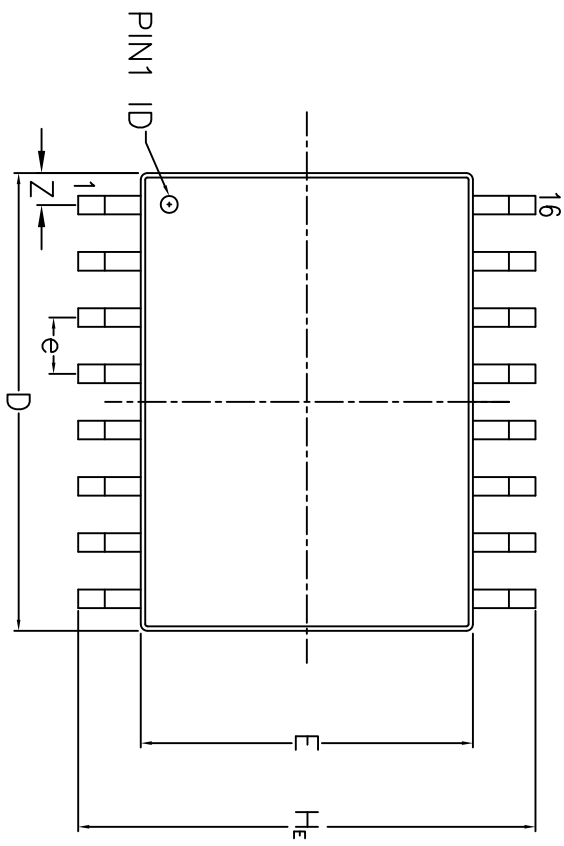


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	2/25/16	J.H



DIMENSIONS OF SUB-GROUP B1	
A max	2.65
bp min	0.35
bp max	0.49
e nom	1.27
He min	10.00
He max	10.65
Lpmin	0.61
Z max	0.79

2. WEIGHT ≤ 0.5 g
3. BODY MATERIAL LOW STRESS EPOXY
4. LEAD MATERIAL Cu-ALLOY
5. LEAD FINISH SOLDER PLATING
6. LEAD FORM Z-BENDS

DIMENSIONS OF SUB-GROUP C1	
A min	2.35
A1 min	0.10
A1 max	0.30
A2 min	2.25
A2 max	2.45
c min	0.23
c max	0.32
D min*	10.21
D max*	10.46
E min*	7.40
E max*	7.60
k min	0.25
θ max	0°
θ max	8°

* WITHOUT MOLD FLASH

TOLERANCES UNLESS SPECIFIED			
DECIMAL	ANGULAR	6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572	
xxx±	±	WWW.IDT.COM	
xxxx±		TITLE PSG16 PACKAGE OUTLINE	
APPROVALS	DATE	SIZE	DRAWING No.
DRAWN	2/25/16	C	PSC-4007-01
CHECKED		DO NOT SCALE DRAWING	REV
			00
			1 OF 1